

SPECIFICATION

宏致電子股份有限公司

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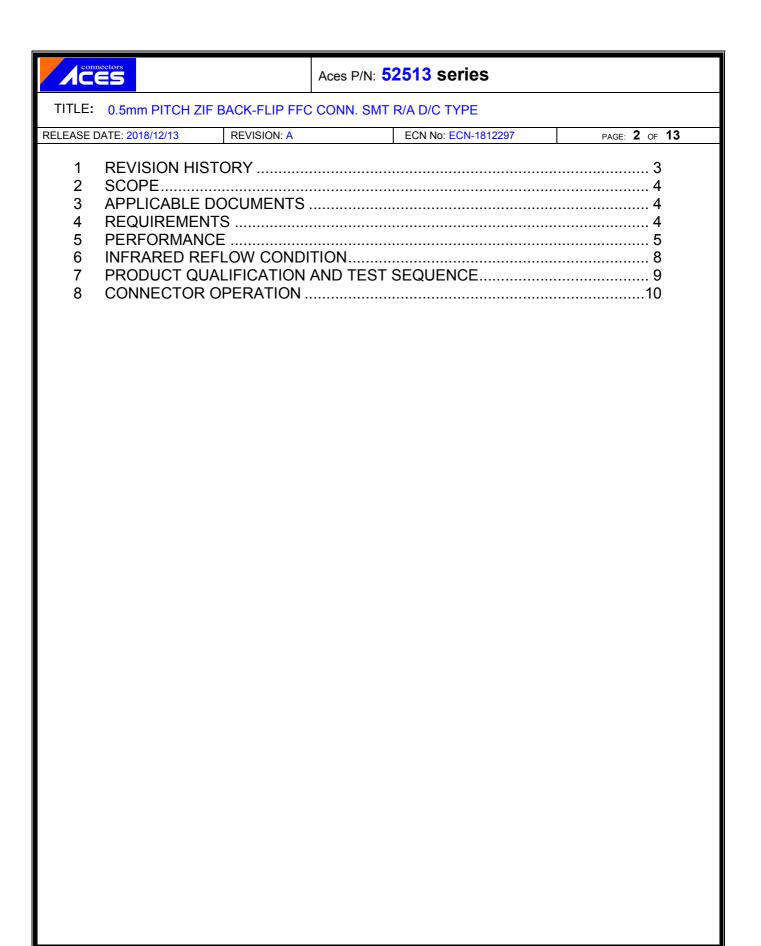
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SPEC. NO.:	PS-525	513-XXXXX-XXX	REVISION:	A	-
PRODUCT N	IAME:	0.5mm PITCH ZIF	BACK-FLIP FFC CON	N. SMT R/A D/	C TYPE
PRODUCT N	(O:	52513 SERIES			

PREPARED:	CHECKED:	APPROVED:
ZHUWEI	BRAVE	BRAVE
DATE: 2018/12/13	DATE: 2018/12/13	DATE: 2018/12/13



Revision History Rev. ECN.# Revision Description Prepared Date Da	ASE DATE: 2018/12/13 REVISION: A ECN No: ECN-1812297 PAGE: 3 OF 13 Revision History Rev. ECN # Revision Description Prepared Date				Aces P/N: 52513 series						
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Rev. ECN# Revision Description Prepared Date	Rev. ECN # Revision Description Prepared Date	ASE DATE	: 2018/12/13	REVISION: A	ECN No: ECN-1812297	PAG	ge: 3 of 13				
		Revisi	Revision History								
CENTIOLES NEW PROJECT SPEC FOR APPLIO/0363 ZHOWET ZU16/12/13	O ECN-161229/ NEW PROJECT SPEC FOR APULT/10363 ZHOWEI 2016/12/13			NEW DDO	Revision Description	Prepared					
		0	ECIN-1012297	NEW PRO	JECT SPEC FOR APD 1070363	ZHUVVEI	2016/12/13				



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2 SCOPE

This specification covers performance, tests and quality requirements for 0.5 mm pitch, ZIF Back-Flip FFC connector. SMT R/A D/C TYPE

3 APPLICABLE DOCUMENTS

EIA-364: ELECTRONICS INDUSTRIES ASSOCIATION

4 REQUIREMENTS

- 4.1 Design and Construction
 - 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
 - 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.
- 4.2 Materials and Finish
 - 4.2.1 Contact: High performance copper alloy (Phosphor Bronze)

Finish: (a) Contact Area: Refer to the drawing.

- (b) Under plate: Refer to the drawing.
- (c) Solder area: Refer to the drawing.
- 4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.3 Actuator: Thermoplastic or Thermoplastic High Temp., UL94V-0
- 4.2.4 Fitting Nail: High performance copper alloy (Brass)

Finish: Refer to the drawing.

- 4.3 Ratings
 - 4.3.1 Working Voltage Less than 36 Volts AC (per pin)
 - 4.3.2 Voltage: 50 Volts AC (per pin)
 - 4.3.3 Current: DC 0.5 Amperes (per pin)
 - 4.3.4 Operating Temperature : -40°C to +85°C



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5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard						
Examination of Product	Product shall meet requirements of applicable product drawing and specification.	Visual, dimensional and functional per applicable quality inspection plan.						
	ELECTRICAL							
Item	Requirement	Standard						
Low Level Contact Resistance	60 m Ω Max. (initial)per contact 20 m Ω Max. change allowed	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)						
Insulation Resistance	500 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)						
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	300 VAC Min. at sea level for 1 minute. Test between adjacent contacts of unmated connectors. (EIA-364-20)						
Temperature Rise 30°C Max. Change allowed		Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70, METHOD1,CONDITION1)						



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MECHANICAL						
Item	Requirement	Standard				
Durability	20 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)				
FPC Retention Force	15 gf/pin MIN.	A connector shall be soldered on a board and insert the actuator, pull the FPC at the speed rate of 25.4 ± 3 mm/min.				
Terminal /Housing Retention Force	50 gf MIN.	Operation Speed: 25.4 ± 3 mm/minute. Measure the contact retention force with tester.				
Fitting Nail /Housing Retention Force	50 gf MIN.	Operation Speed: 25.4 ± 3 mm/minute. Measure the contact retention force with tester.				
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)				
Shock (Mechanical)	1 μs Max.	Subject mated connectors to 50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be 100mA maximum for all contacts. (EIA-364-27, test condition A)				



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ENVIRONMENTAL						
ltem	Requirement	Standard				
Resistance to Reflow Soldering Heat	See Product Qualification and Test Sequence Group 10 (Lead Free)	Pre Heat: 150°C~180°C, 60~120sec. Heat: 230°C Min., 40sec Min. Peak Temp.: 260°C Max, 10sec Max. IR reflow cycles: 2 times				
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles.				
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)				
Temperature Life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to				
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold plating 3u" for 48 hours. (EIA-364-26)				
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)				
Hand Soldering Temperature Resistance	Appearance: No damage	T≧350°C, 3sec at least.				

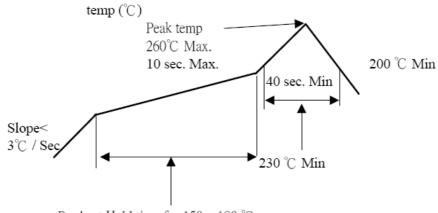
Note. Flowing Mixed Gas shell be conduct by customer request.

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6 INFRARED REFLOW CONDITION

TEMPERATURE CONDITION GRAPH (TEMPERATURE ON BOARD PATTERN SIDE)



Pre-heat Hold time for $150 \sim 180$ °C is $60 \sim 120$ sec.

connectors

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7 PRODUCT QUALIFICATION AND TEST SEQUENCE

Test or Examination		Test Group								
		2	3	4	5	6	7	8	9	10
				Т	est Se	quenc	e			
Examination of Product	1、3			1 . 7	1 . 6	1 \ 4			1	1
Low Level Contact Resistance		1 \ 5	1 • 4	2 \ 10	2 . 9	2 ` 5			3	
Insulation Resistance				3 . 9	3 . 8					
Dielectric Withstanding Voltage				4 \ 8	4 · 7					
Temperature Rise	2									
Durability		3								
Vibration			2							
Shock (Mechanical)			3							
Thermal Shock				5						
Humidity				6						
Temperature Life					5					
Salt Spray(Only For Gold Plating)						3				
Solder ability							1			
FPC Retention Force		2 · 4								
Terminal / Housing Retention Force								1		
Fitting Nail /Housing Retention Force								2		
Resistance to Soldering Heat									2	
Hand Soldering Temperature Resistance										2
Sample Size	2	4	4	4	4	4	2	4	4	4



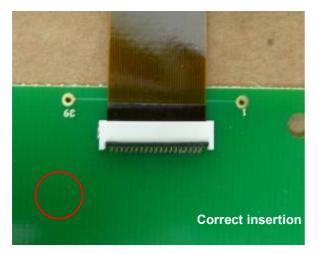
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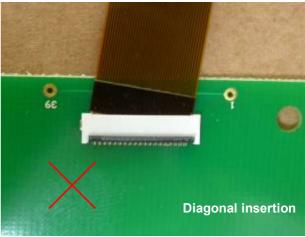
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8 CONNECTOR OPERATION

Exercise care when handling connectors. Follow recommendations given below.

- A. Please open and close the actuator with the connector is mounted on the P.C.Board, and the FPC inserted. The actuator might not come off from the opening and shutting of the actuator in the state that FPC is not inserted and do not do, please.
- B. FPC Correct insertion verification
 A visual comparison of the edge of the housing opening and the FPC pattern boundary will
 prevent diagonal insertion and partial insertion errors.





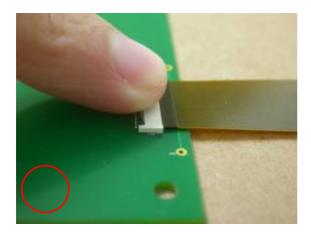


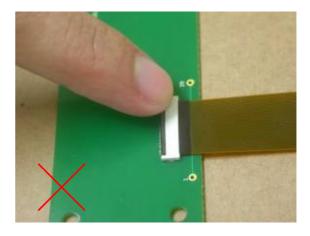
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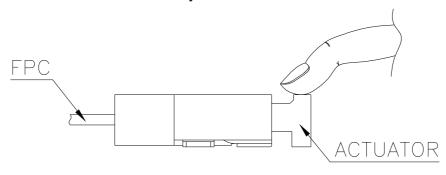
C. Locking

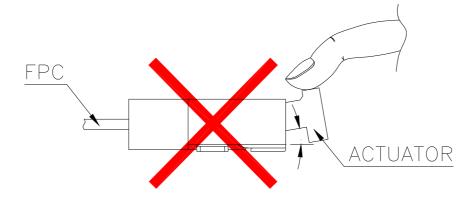
After FPC/FFC insertion, rotate the actuator down to a full stop, pushing it at the center.





About the lock operation When you lock, it is recommended what the actuator does as a whole, and the actuator was shut surely.





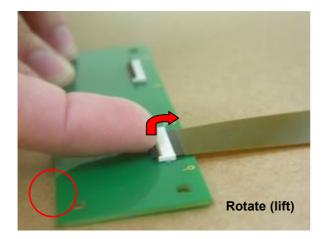


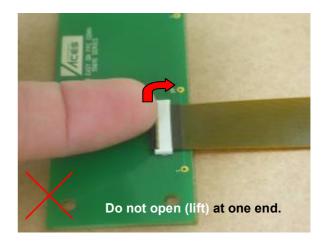
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D. Lock release

Carefully rotate the actuator up to 90°, lifting it at the center.





 The actuator opens by rotating it in the direction OPPOSITE to the direction of the insertion of the FPC. DO NOT attempt to open it from the same side as the insertion of the FPC.

